



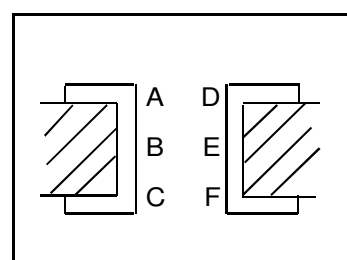
MICRO-SECTIONING REPORT

TEST METHOD(测试方法): IPC-TM-650 2. 1. 1.2

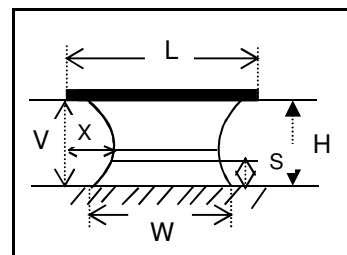
APPARATUS(仪器): MICROSCOPE(显微镜): 50X 100X 400X 600X unit(单位):um(微米)

Testing Item (测试项目)	Base Cu thk. (基材铜箔厚度) (refer to picture 2)	Hole wall Cu thk. (孔壁铜厚) (refer to picture 1)	Surface conductor thk. (成品铜厚) (refer to picture 2)	Nickel thk. (镍厚)	Solder Mask (阻焊油厚) (refer to picture 3)	Sn thickness (锡厚)
Requirement (要求)	Outer:17.5 Inner:35.0	20.00	35.00		10.00	
Result (结果)						

Hole wall Cu thickness (refer to picture 1)								
NO	Symbol	A	B	C	D	E	F	Average
1	Cu							
2								
3								
4								
5								



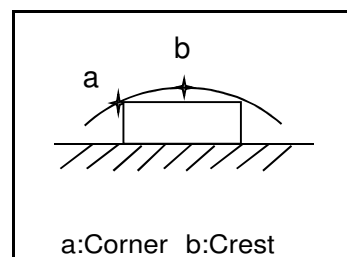
Hole wall Cu (picture 1)



Surface conductor thk.
(picture 2)

V/X: Etch Factor ≥ 1.0 (refer to picture 2)

V/X: _____ LINE WIDTH: L: _____ W: _____



a:Corner b:Crest
Solder Mask thk.
(picture 3)

DISPOSITION: ACCEPTED REJECTED

PREPARED BY: _____ DATE: _____

APPROVED BY: _____ DATE: _____